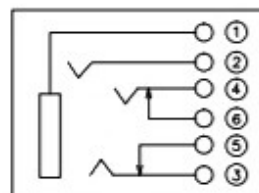


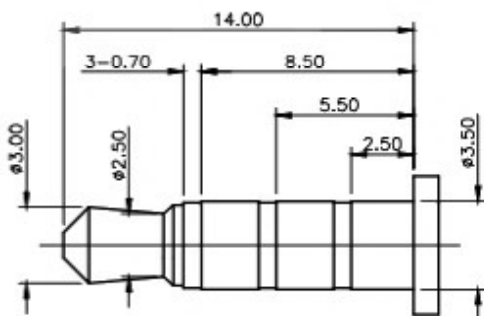
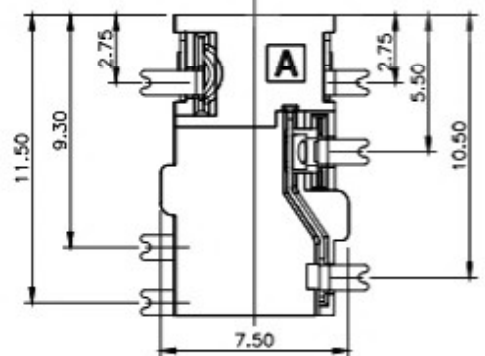
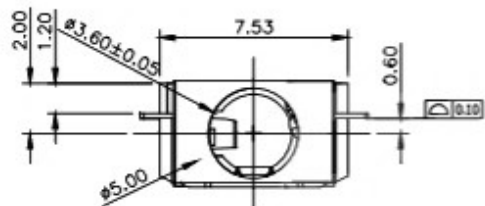
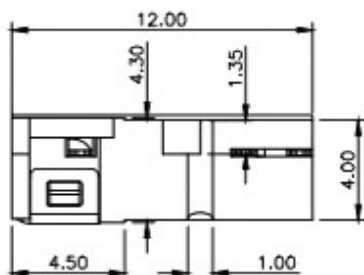
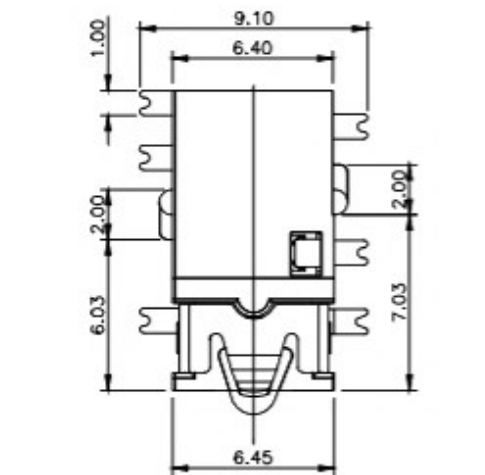
NOTES:

1. REQUEST OF THE SPECIFICATION:

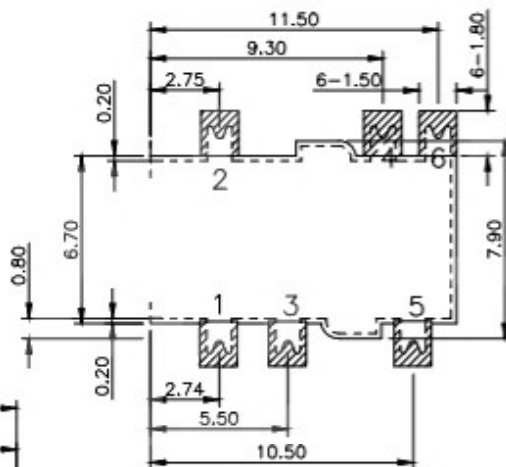
- 1.1 CONTACT CURRENT RATING: 1A;
- 1.2 CONTACT RESISTANCE: 100 mΩ MAX.;
- 1.3 INSULATION RESISTANCE: 100MΩ MIN.;
- 1.4 DIELECTRIC WITHSTANDING: 500V AC MIN.;
- 1.5 DURABILITY: 5,000 CYCLES MIN.;
- 1.6 CONNECTOR MATING FORCES: 29.8N (3.00Kgf) MAX.;
- 1.7 CONNECTOR UNMATING FORCES: 2.98N(0.30Kgf) MIN.;



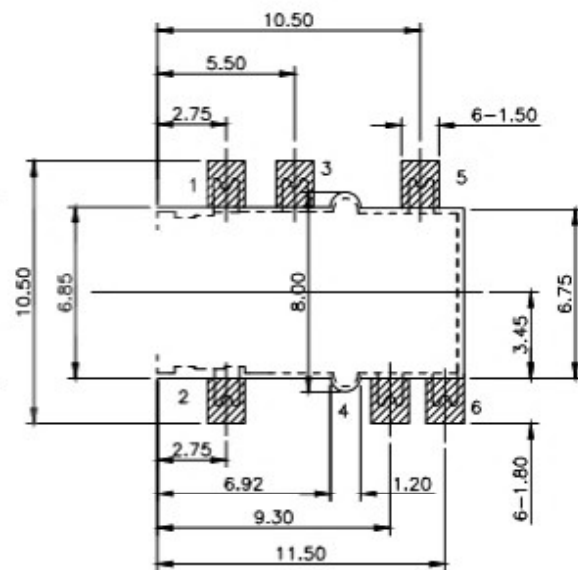
SCHEMATIC



($\phi 3.50\text{mm}$ 4 POLE PLUG DETAIL DRAWING)



正贴 P.C.B LAYOUT
TOP VIEW



反贴 P.C.B LAYOUT
TOP VIEW

ITEM	NAME	QTY	DESCRIPTION	NOTE
7	TERMINAL 4#	1	PHOSPHOR BRONZE; NICKEL(40%/MIN.) UNDER PLATING OVERALL GOLD FLASH ON SOLDER AREA	T=0.20
6	TERMINAL 5#	1	PHOSPHOR BRONZE; NICKEL(40%/MIN.) UNDER PLATING OVERALL GOLD FLASH ON SOLDER AREA	T=0.20
5	TERMINAL 4#	1	SUS304; THE BOTTOM OF THE NICKEL(40%/MIN.); THE WHOLE GOLD FLASH PLATING.	T=0.20
4	TERMINAL 5#	1	SUS304; NICKEL(40%/MIN.) UNDER PLATING OVERALL GOLD FLASH ON SOLDER AREA GOLD FLASH ON CONTACT AREA	T=0.20
3	TERMINAL 2#	1	PHOSPHOR BRONZE; NICKEL(40%/MIN.) UNDER PLATING OVERALL GOLD FLASH ON SOLDER AREA GOLD FLASH ON CONTACT AREA	T=0.20
2	TERMINAL 1#	1	SUS304; THE BOTTOM OF THE NICKEL(40%/MIN.); THE WHOLE GOLD FLASH PLATING.	T=0.20
1	HOLDING	1	PPA COLOR BLACK	



东莞市溪榜电子有限公司

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PART NAME		PHONE JACK (SMD)		DRAWING		Y.C.Zhang		DWG.No.	
PART NO.		PJ-399E-W		CHECK		G.C.Chen		REV. A1	
UNIT: mm	TOLERANCE	UP TO 5	±0.2	ANGLE	APPROVAL		DATE		
	OTHERWISE	ABOVE 5~30	±0.3		SCALE		PAGE		
		ABOVE 30	±0.5	0°±3'	4:1		1 OF 1		